

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

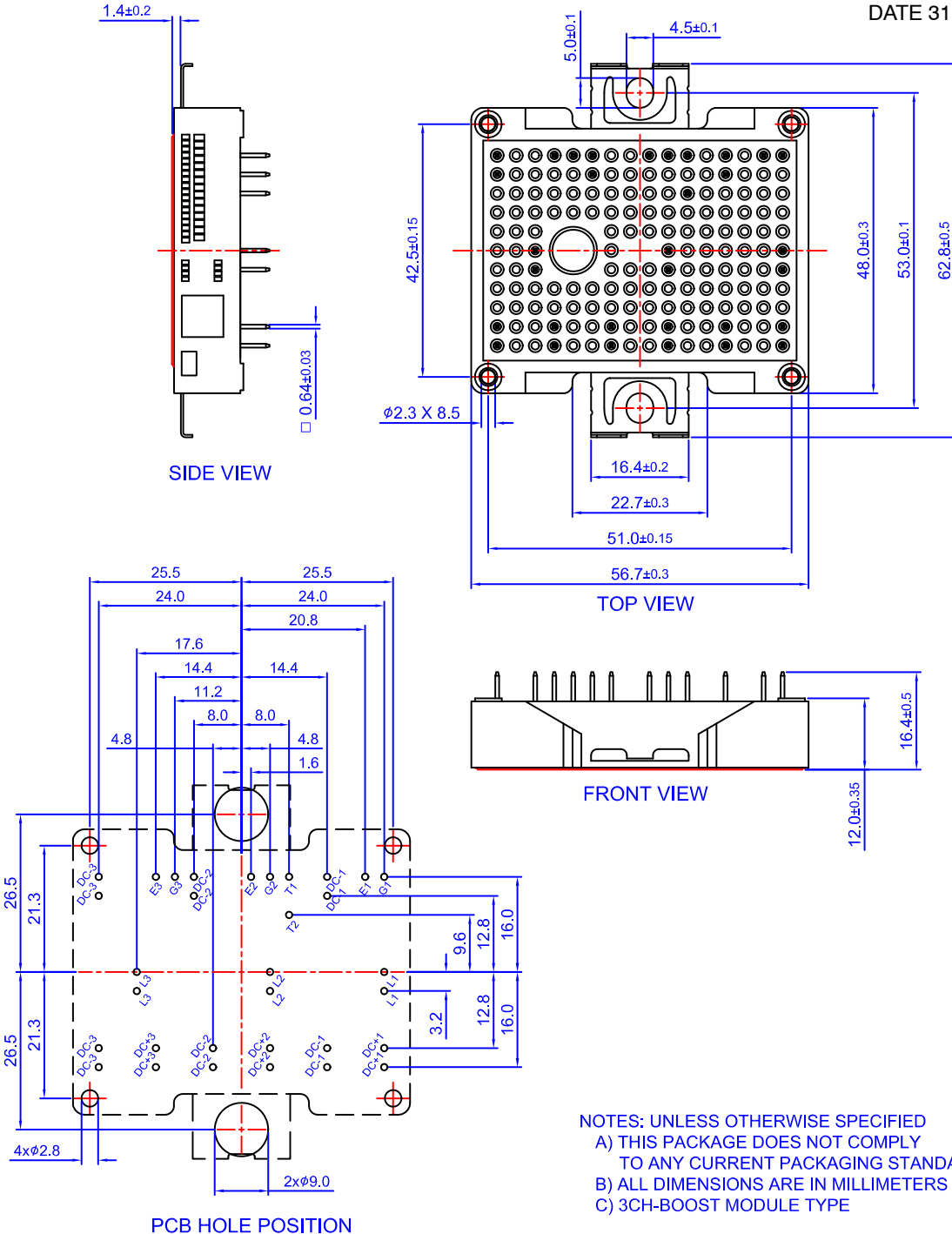
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### HF2CA-N32 / 32LD, HPM, F2 PKG, SOLDERING TERMINAL, 3CH BOOST MODULE

CASE MODCS  
ISSUE O

DATE 31 DEC 2016



NOTES: UNLESS OTHERWISE SPECIFIED  
 A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD  
 B) ALL DIMENSIONS ARE IN MILLIMETERS  
 C) 3CH-BOOST MODULE TYPE

- PIN-GRID 3.2mm  
 - TOLERANCE OF PCB HOLE PATTERN  $\phi 0.1$

<b>DOCUMENT NUMBER:</b>	<b>98AON13518G</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>DESCRIPTION:</b>	<b>HF2CA-N32 / 32LD, HPM, F2 PKG, SOLDERING TERMINAL</b>	<b>PAGE 1 OF 1</b>

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